EI-27003: Electronics Devices and Circuits Lecture - 10

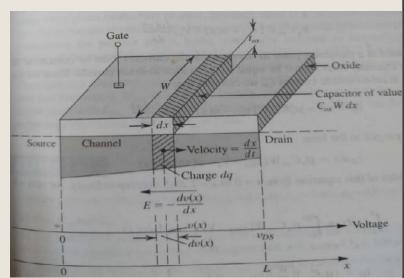
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LECTURE - 10

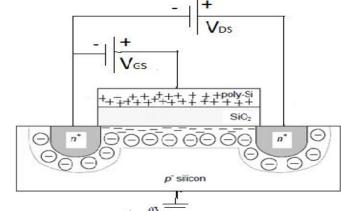
Year: 2020-21

Derivation of Drain Current ID

- Let us assume that V_{GS} is applied between Gate and Source with V_{GS}>V_t to induce channel.
- Also assume that VDS is applied between drain and source.
- Let us consider triode region in which V_{DS} < (V_{GS}-V_t)



- In this case channel will have tapered shape as shown in cross sectional view.
- Now gate is connected to +ve plate of Battery have +ve charges on it.
- Channel formed is of electrons (-ve), have -ve charges on it.
- ➤ In between these +ve and –ve layers, there is SiO₂ layer which is dielectric.



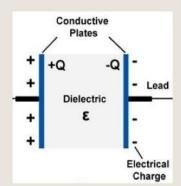
Derivation.....

 Hence the gate and channel region forms a parallel plate capacitor. If capacitance per unit gate area is denoted as C_{ox} and thickness of oxide layer is t_{ox}, then

$$C_{ox} = \frac{\varepsilon_{ox}}{t_{ox}} \quad ----- (1)$$

 \triangleright Where: ε_{ox} is the permittivity of silicon dioxide

$$\varepsilon_{ox}$$
= 3.9 x ε_{o} = 3.9 x 8.8854x10⁻¹²=3.45x10⁻¹¹F/m



- Now consider cross sectional view and consider infinitesimal strip of the gate at distance x from source.
- \triangleright The capacitance of this strip is = C_{ox} .w.dx -----(2)
- To find the charge stored on this strip of gate capacitance, we multiply the capacitance by effective voltage between gate and channel at point x.
- This effective voltage at point x will be = [V_{GS}-V_t-V(x)] -----(3)
- Hence electron charge dq in infinitesimal portion of channel at point x is

$$dq = -C_{ox}.w.dx [V_{GS}-V_t-V(x)]$$
 -----(4)

-ve sign is negative charge.

Derivation.....

 The voltage VDS produces electric field along the channel in the negative x direction. At point x this field can be expressed as;

$$\mathsf{E}(\mathsf{x}) = -\frac{dV(x)}{dx} \quad -----(5)$$

The electric field E(x) causes the electron charge dq to drift towards the drain with velocity dx/dt

$$\frac{dx}{dt} = -\mu_n E(x) = \mu_n \frac{dV(x)}{dx} - ----(6)$$

- \triangleright Where μ_n is the mobility of electrons in the channel.
- Thus the resulting drift current 'i' is obtained as:

$$i = \frac{dq}{dt} \text{ or } \frac{dq}{dx} \frac{dx}{dt}$$
 -----(7)

> Substitute $\frac{dq}{dx}$ from eq.(4) and $\frac{dx}{dt}$ from eq.(6), then

$$i = -\mu_n C_{ox}.w. [V_{GS}-V_t-V(x)] \frac{dV(x)}{dx}$$
 -----(8)

Derivation.....

- Although evaluated at a particular point in the channel, the drift current (electron current) 'i' must be constant at all points along the channel.
- As we are interested in drain current (conventional current) I_D:

$$I_D = -i = \mu_n C_{ox}.w. [V_{GS}-V_t-V(x)] \frac{dV(x)}{dx}$$
 -----(9)

Rearrange this equation:

$$I_D dx = \mu_n C_{ox}.w. [V_{GS}-V_t-V(x)] dV(x)$$
 -----(10)

Integrating both sides of this equation from x=0 to x=L correspondingly for V(0)=0 to V(L)=V_{DS}

$$\int_{0}^{L} I_{D} dx = \int_{0}^{V_{DS}} \mu_{n} C_{ox}.w. [V_{GS} - V_{t} - V(x)] dV(x) -----(11)$$

Solving this integration gives:

$$I_D = \mu_n C_{ox}(W/L) [(V_{GS} - V_t)V_{DS} - \frac{1}{2}V_{DS}^2]$$
 for $V_{DS} < (V_{GS} - V_t)$ triode region -----(12)

Drain Current I_D for Saturation Region

- As we know if V_{DS} becomes equals to (V_{GS}-V_t), the channel gets pinched-off and NMOS is just on verge of Saturation.
- So equation (12) becomes:

$$I_{D} = \mu_{n}C_{ox}(W/L) [(VGS-Vt)V_{DS} - \frac{1}{2}V^{2}_{DS}] -----(12)$$
Substitute $V_{DS} = (V_{GS}-V_{t})$

$$I_{D} = \mu_{n}C_{ox}(W/L) [(VGS-Vt)(VGS-Vt) - \frac{1}{2}(VDS-Vt)2]$$

$$I_D = \frac{1}{2} \mu_n C_{ox}(W/L)(VDS-Vt)2$$
 for $V_{DS} \ge (V_{GS}-V_t)$ Saturation Region

- \triangleright Here $\mu_n C_{ox}$ is constant and is called as Process Trans-conductance Parameter.
- ▶ It is denoted by K_n and has dimensions of A/V²

$$I_D = K_n(W/L) [(VGS-Vt)V_{DS} - \frac{1}{2}V^2_{DS}]$$
 Triode region

$$I_D = \frac{1}{2}K_n(W/L)(VDS-Vt)^2$$
 Saturation region

Its time for Quiz

https://forms.gle/TWepKdJg1hMjJZNV6